

Title (en)

AID FOR ELECTRICAL CONTACTING OF HIGH-TEMPERATURE FUEL CELLS AND METHOD FOR PRODUCTION THEREOF

Title (de)

HILFSMITTEL ZUR ELEKTRISCHEN KONTAKTIERUNG VON HOCHTEMPERATUR-BRENNSTOFFZELLEN UND VERFAHREN ZU DESSEN HERSTELLUNG

Title (fr)

MOYEN PERMETTANT LA MISE EN CONTACT ÉLECTRIQUE DE PILES À COMBUSTIBLE À HAUTE TEMPÉRATURE ET SON PROCÉDÉ DE FABRICATION

Publication

EP 2193566 A1 20100609 (DE)

Application

EP 08804802 A 20080926

Priority

- EP 2008062925 W 20080926
- DE 102007046976 A 20070928

Abstract (en)

[origin: CA2700951A1] The subject matter of the invention is a double-sided adhesive metal-based tape for use as contacting aid for SOFC fuel cells. The new adhesive tape means a significant simplification in comparison to the present use of a liquid adhesive. The simple, low-cost production without special tools and the simplicity of use in a fuel cell stack provide an excellent option for minimizing costs during assembly and permitting large-scale production. The double-sided metal-based adhesive tape is suitable for simplifying the construction of cell bundles. The advantages of the metal-based adhesive tape in comparison to conventional contacting are a better control of the layer thickness, a cleaner and more accurate application without curing time and the potential for automation of large-scale production.

IPC 8 full level

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CPC (source: EP KR US)

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Citation (search report)

See references of WO 2009043818A1

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Designated extension state (EPC)

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DOCDB simple family (publication)

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